

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	1187	(cure or cured or curing) adj10 (polymeric adj3 material)	USPAT; US-PGP UB; EPO; JPO; DERWEN T	2002/11/26 15:21
2	BRS	L2	48	1 same (hard or harden or hardening)	USPAT; US-PGP UB; EPO; JPO; DERWEN T	2002/11/26 15:27
3	BRS	L3	19	wafer same polymeric same bump	USPAT; US-PGP UB; EPO; JPO; DERWEN T	2002/11/26 15:35
4	BRS	L4	1	(remove or removing or removed) adj10 (polymeric adj3 material) same expose same bump	USPAT; US-PGP UB; EPO; JPO; DERWEN T	2002/11/26 15:36
5	BRS	L5	23	(form or forming) adj10 polymeric same bump	USPAT; US-PGP UB; EPO; JPO; DERWEN T	2002/11/26 15:44
6	BRS	L6	31	(remove or removing or removed) same (expose or exposed or exposing) same (conductive adj bump)	USPAT; US-PGP UB; EPO; JPO; DERWEN T	2002/11/26 15:53

	Type	L #	Hits	Search Text	DBs	Time Stamp
7	BRS	L7	26	(form or forming or formed) adj10 (conductive adj3 bump) adj10 wafer	USPAT; US-PGP UB; EPO; JPO; DERWEN T	2002/11/26 15:54

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	173	(cure or cured or curing) adj10 (polymeric) same (hard or harden or hardening)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2002/11/26 17:02
2	BRS	L2	1	1 and (conductive adj bump)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2002/11/26 17:11
3	BRS	L3	7	1 and (bump or bumps or solder or solders)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2002/11/26 17:12